



 ${\bf Part\ Number:} \qquad {\bf XZM2ACR45W-2}$

3.5x2.8mm SMD CHIP LED LAMP

PRELIMINARY SPEC

Features

- Single color.
- Suitable for all smt assembly and solder process.
- Ideal for backlighting.
- Available on tape and reel.
- Package : 500pcs / reel.
- Moisture sensitivity level : level 3.
- \bullet RoHS compliant.

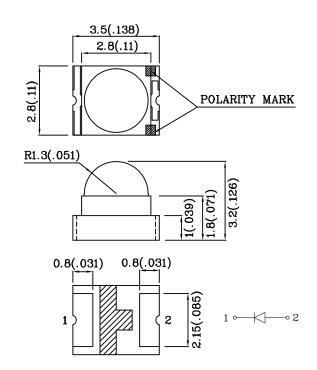




Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (TA=25°C)		M2ACR (AlInGaP)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA
Power Dissipation	Рт	84	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	,



Operating Characteristics (Ta=25°C)		M2ACR (AlInGaP)	Unit
Forward Voltage (Typ.) (IF=20mA)	$V_{\rm F}$	2.2	V
Forward Voltage (Max.) (IF=20mA)	$V_{\rm F}$	2.8	V
Reverse Current (Max.) (VR=5V)	IR	10	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λΡ	640	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λ D	630	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	Δλ	25	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	С	27	pF

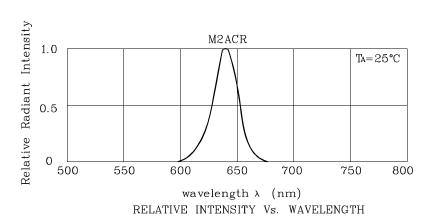
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XZM2ACR45W-2	Red	AlInGaP	Water Clear	2200	3790	640	40°
Published Date : .	JAN 09,2009	Drawi	ng No : XDSB2762	V1	Checkee	d : B.L.LIU	P.1/4



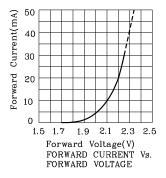
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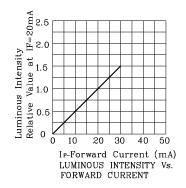
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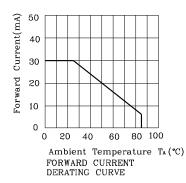


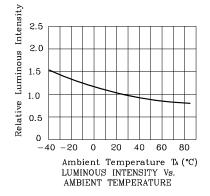


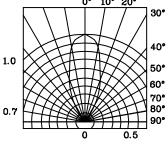
❖ M2ACR











SPATIAL DISTRIBUTION

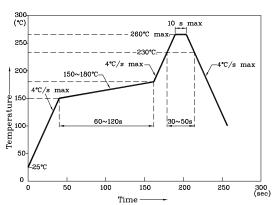




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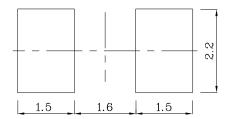
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

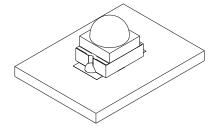


NOTES:

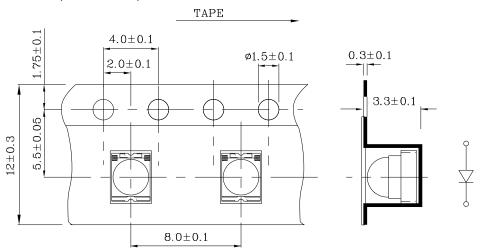
- 1. Maximum soldering temperature should not exceed 260°c.
- 2. Recommended reflow temperature: 145°c-260°c.
- 3. Do not put stress to the epoxy resin during high temperatures conditions.
- ❖ Recommended Solering Pattern (Units: mm; Tolerance:± 0.1)



♦ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

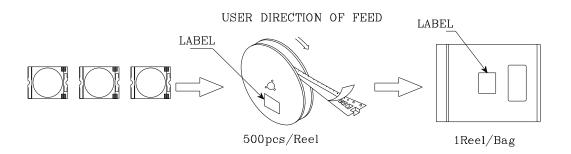


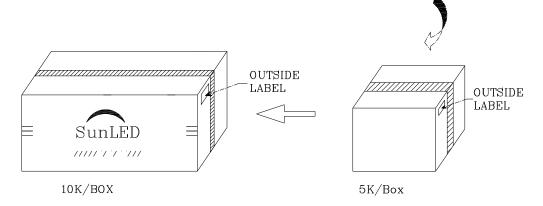
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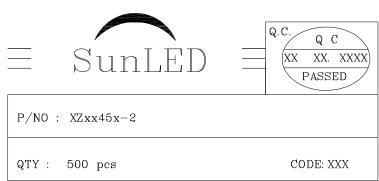
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PACKING & LABEL SPECIFICATIONS

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S/N: XX

LOT NO:

RoHS Compliant

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